Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model **[List multiple models if applicable.]**
HP EVA6400 Dual Controller Array / AJ757A
HP EVA8400 14GB Dual Controller Array / AJ758A
HP EVA8400 22GB Dual Controller Array / AJ847A
HP EVA6400 for Storage Rack / AP884A
HP EVA8400 14GB Cache for Storage Rack / AP885A
HP EVA8400 22GB Cache for Storage Rack / AP888A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6400’s = 16 8400’s = 18
Batteries	All types including standard alkaline and lithium coin or button style batteries	6400’s = 24 8400’s = 36
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		6400’s = 18 8400’s =
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Screw Driver	# 2
Flat head Screw Driver	Medium
Pry Tool	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment: Most hardware is common between the 6400 and 8400 models. Specific differences are noted below.

1. Remove top cover. See figure 1.
2. Remove 2 power supplies . See figure 2.
3. Open power supplies using a small Phillips screw driver. 8 screws on each individual power supply. Pry off the 4 capacitors as shown in figure 3.
4. Remove battery packs from Chassis as shown in figure 4. Units may have up to 4 individual battery packs based on the model of controller. Note: 2 batteries may be located behind the LDC display.
5. Open the cover of all the battery packs with a flat head screw driver. Remove the individual battery packs and pca and dispose of according to local laws. See figure 5.
6. Remove the 10 capacitors from the power supply daughter board as shown in Figure 6. The Daughter board can be removed with a Phillips screw driver.
7. Other PCA's can be removed with the Phillips head screw driver and disposed of according to local laws.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1.

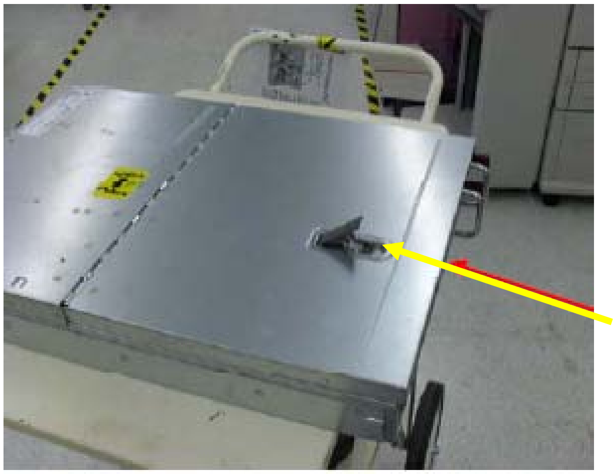

Figure 2.

Figure 3.

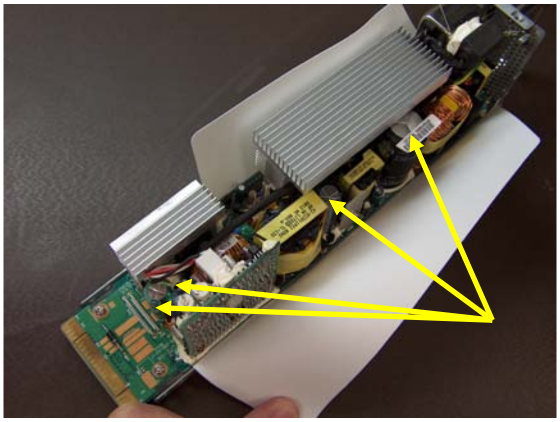

Figure 4.

Figure 5.

Figure 6.